

# **PS8101**

1 Mbps, HIGH CMR ANALOG OUTPUT TYPE 5-PIN SOP (SO-5) PHOTOCOUPLER R08DS0138EJ0100 Rev.1.00 Oct.29.2018

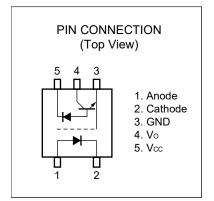
#### DESCRIPTION

The PS8101 is an optically coupled isolator containing an AlGaAs LED on the light emitting diode (input side) and a PIN photodiode and a high-speed amplifier transistor on the output side on one chip.

This is a plastic SOP (Small Out-line Package) type for high density applications.

#### **FEATURES**

- High common mode transient immunity (CM<sub>H</sub>, CM<sub>L</sub> =  $\pm 15$  kV/ $\mu$ s MIN.)
- Small package (SO-5)
- High supply voltage ( $V_{CC} = 35 \text{ V}$ )
- High isolation voltage (BV = 3 750 Vr.m.s.)
- High-speed response ( $t_{PHL} = 0.8 \mu s \text{ MAX.}$ ,  $t_{PLH} = 1.2 \mu s \text{ MAX.}$ )
- Ordering number of taping product: PS8101-F3: 2 500 pcs/reel
- Pb-Free product
- · Safety standards
  - UL approved: UL1577, Single protection
  - CSA approved: CAN/CSA-C22.2 No. 62368-1, Basic insulation
  - VDE approved: DIN EN 60747-5-5 (Option)

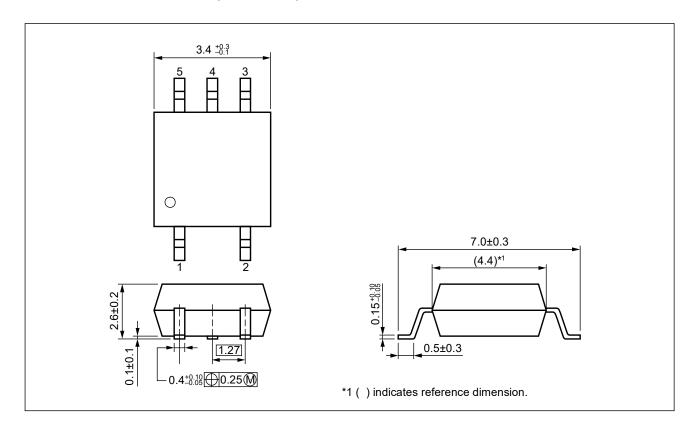


#### **APPLICATIONS**

- Computer and peripheral manufactures
- General purpose inverter
- Substitutions for relays and pulse transformers
- Power supply

Start of mass production Jul.2007

## PACKAGE DIMENSIONS (UNIT: mm)

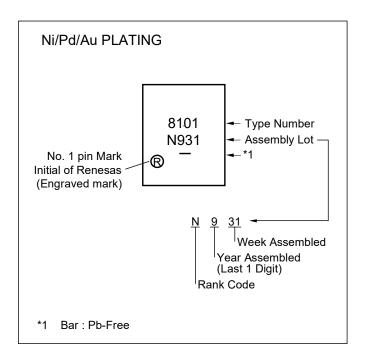


Weight: 0.08g (typ.)

## PHOTOCOUPLER CONSTRUCTION

Parameter	PS8101
Air Distance (MIN.)	4.2 mm
Creepage Distance (MIN.)	4.2 mm
Isolation Distance (MIN.)	0.2 mm

### **MARKING EXAMPLE**



### **ORDERING INFORMATION**

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number*1
PS8101	PS8101-AX	Pb-Free	20 pcs (Tape 20 pcs cut)	Standard products	PS8101
PS8101-F3	PS8101-F3-AX	(Ni/Pd/Au)	Embossed Tape 2500 pcs/reel	(UL, CSA approved)	
PS8101-V	PS8101-V-AX		20 pcs (Tape 20 pcs cut)	UL, CSA,	
PS8101-V-F3	PS8101-V-F3-AX		Embossed Tape 2 500 pcs/reel	DIN EN 60747-5-5 approved	

Notes: \*1. For the application of the Safety Standard, following part number should be used.

### ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25°C, unless otherwise specified)

	Parameter	Symbol	Ratings	Unit	
Diode	Forward Current	l <sub>F</sub>	25	mA	
	Reverse Voltage	VR	5.0	V	
	Power Dissipation*1	Po	45	mW	
Detector	Supply Voltage	Vcc	35	V	
	Output Voltage	Vo	35	V	
	Output Current	lo	8.0	mA	
	Power Dissipation *2	Pc	100	mW	
Isolation \	oltage *3	BV	3 750	Vr.m.s.	
Operating	Ambient Temperature	TA	–55 to +100	°C	
Storage T	emperature	T <sub>stg</sub>	-55 to +125	°C	

Notes: \*1. Reduced to 0.45 mA/°C at T<sub>A</sub> = 25°C or more.

<sup>\*2.</sup> Reduced to 1.00 mW/°C at  $T_A$  = 25°C or more.

<sup>\*3.</sup> AC voltage for 1 minute at  $T_A$  = 25°C, RH = 60% between input and output. Pins 1-2 shorted together, 3-5 shorted together.

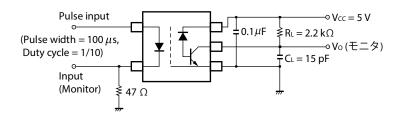
# ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C, unless otherwise specified)

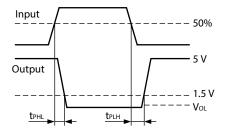
	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V <sub>F</sub>	I <sub>F</sub> = 16 mA		1.7	2.2	V
	Reverse Current	I <sub>R</sub>	V <sub>R</sub> = 3 V			10	μA
	Forward Voltage Temperature Coefficient	ΔVε/ΔΤΑ	I <sub>F</sub> = 16 mA		-2.1		mV/°C
	Terminal Capacitance	Ct	V = 0 V, f = 1 MHz		30		pF
Detector	High Level Output Current	Іон (1)	$I_F = 0 \text{ mA}, V_{CC} = V_0 = 5.5 \text{ V}$		3	500	nA
	High Level Output Current	Іон (2)	I <sub>F</sub> = 0 mA, V <sub>CC</sub> = V <sub>O</sub> = 30 V			100	μА
	Low Level Output	V <sub>OL</sub>	I <sub>F</sub> = 16 mA, V <sub>CC</sub> = 4.5 V,		0.1	0.4	V
	Voltage		I <sub>O</sub> = 1.2 mA				
	Low Level Supply	Iccl	I <sub>F</sub> = 16 mA, V <sub>O</sub> = open,		50		μA
	Current		V <sub>CC</sub> = 30 V				
	High Level Supply Current	Іссн	$I_F = 0$ mA, $V_O = open$ , $V_{CC} = 30$ V		0.01	2	
Coupled	Current Transfer Ratio*1	CTR	I <sub>F</sub> = 16 mA, V <sub>CC</sub> = 4.5 V,V <sub>O</sub> = 0.4 V	15	20	35	%
	Isolation Resistance	R <sub>I-O</sub>	V <sub>I-O</sub> = 1 kV <sub>DC</sub> , RH = 40 to 60%	10 <sup>11</sup>			Ω
	Isolation Capacitance	C <sub>I-O</sub>	V = 0 V, f = 1 MHz		0.4		pF
Propagation (H → L)*2	Propagation Delay Time $(H \rightarrow L)^{*2}$	t <sub>PHL</sub>	$I_F = 16 \text{ mA}, V_{CC} = 5 \text{ V}, R_L = 2.2 \text{ k}\Omega, \\ C_L = 15 \text{ pF}$		0.5	0.8	μS
	Propagation Delay Time $(L \rightarrow H)^{*2}$	t <sub>PLH</sub>			0.6	1.2	
	Common Mode Transient Immunity at High Level Output*3	СМн	I <sub>F</sub> = 0 mA, $V_{CC}$ = 5 V, $R_L$ = 4.1 kΩ, $V_{CM}$ = 1.5 kV	15			kV/μs
	Common Mode Transient Immunity at Low Level Output*3	CML	I <sub>F</sub> = 16 mA, $V_{CC}$ = 5 V, $R_L$ = 4.1 kΩ, $V_{CM}$ = 1.5 kV	-15			

Notes:\*1. CTR rank

K : 20 to 35 (%) N : 15 to 35 (%)

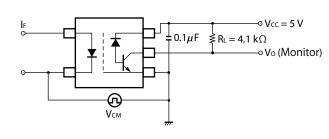
### \*2. Test circuit for propagation delay time

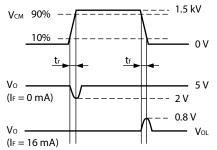




Remark CL includes probe and stray wiring capacitance.

#### \*3. Test circuit for common mode transient immunity

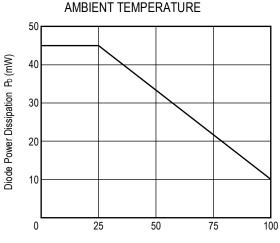




### **USAGE CAUTIONS**

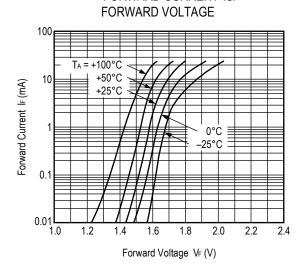
- 1. This product is weak for static electricity by designed with high-speed integrated circuit so protect against static electricity when handling.
- 2. By-pass capacitor of more than  $0.1~\mu F$  is used between  $V_{CC}$  and GND near device. Also, ensure that the distance between the leads of the photocoupler and capacitor is no more than 10 mm.
- 3. Avoid storage at a high temperature and high humidity.
- 4. Do not use adhesives or coating materials including halogens to fix this device.

## TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25°C unless otherwise specified)

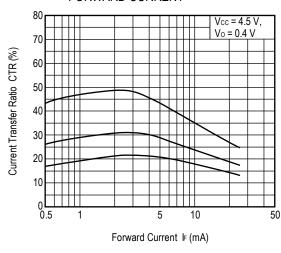


DIODE POWER DISSIPATION vs.

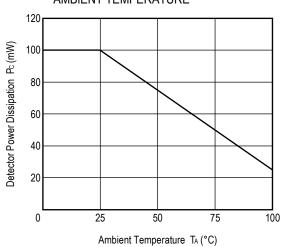




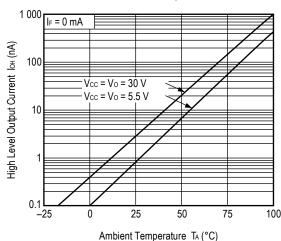
# CURRENT TRANSFER RATIO vs. FORWARD CURRENT



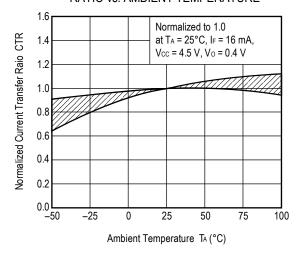
# DETECTOR POWER DISSIPATION vs. AMBIENT TEMPERATURE



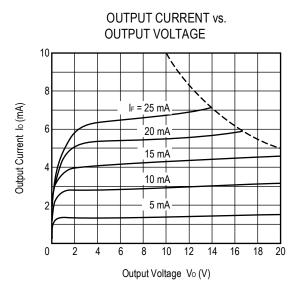
# HIGH LEVEL OUTPUT CURRENT vs. AMBIENT TEMPERATURE



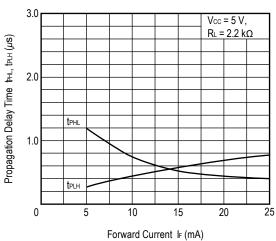
# NORMALIZED CURRENT TRANSFER RATIO vs. AMBIENT TEMPERATURE



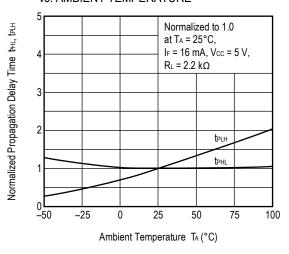
Remark The graphs indicate nominal characteristics.



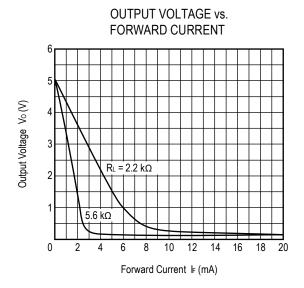




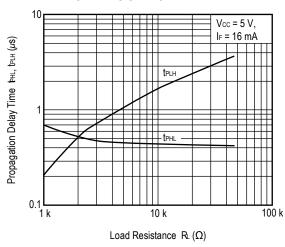
# NORMALIZED PROPAGATION DELAY TIME vs. AMBIENT TEMPERATURE



**Remark** The graphs indicate nominal characteristics.

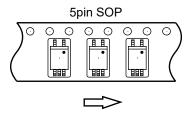


# PROPAGATION DELAY TIME vs. LOAD RESISTANCE

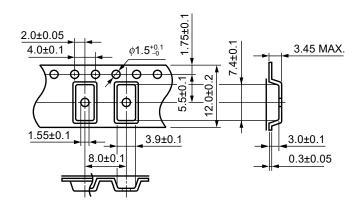


## **TAPING SPECIFICATIONS (UNIT: mm)**

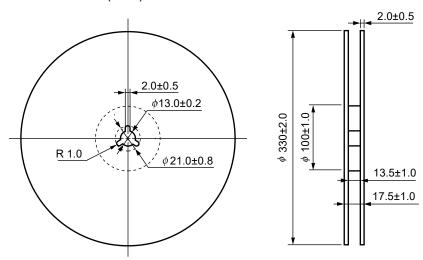




### Outline and Dimensions (Tape)

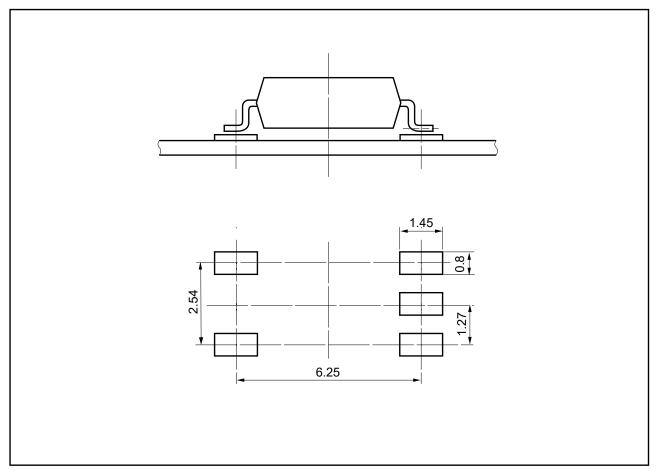


### Outline and Dimensions (Reel)



Packing: 2 500 pcs/reel

# RECOMMENDED MOUNT PAD DIMENSIONS (UNIT: mm)



[5pin SOP]

#### NOTES ON HANDLING

- 1. Recommended soldering conditions
  - (1) Infrared reflow soldering

Peak reflow temperature
 260°C or below (package surface temperature)

Time of peak reflow temperature
 Time of temperature higher than 220°C
 10 seconds or less
 60 seconds or less

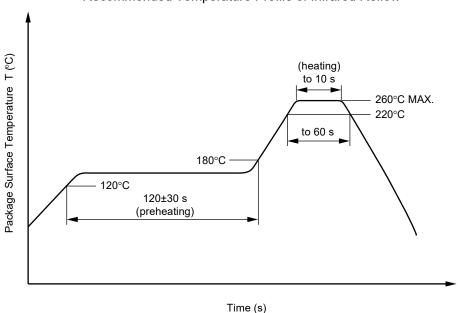
• Time to preheat temperature from 120 to 180°C 120±30 s

Number of reflows

• Flux

Three
Rosin flux containing small amount of chlorine
(The flux with a maximum chlorine content of
0.2 Wt% is recommended.)

#### Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

• Temperature 260°C or below (molten solder temperature)

Time 10 seconds or less

• Preheating conditions 120°C or below (package surface temperature)

Number of times
 Flux
 One (Allowed to be dipped in solder including plastic mold portion.)
 Rosin flux containing small amount of chlorine (The flux with a maximum

chlorine content of 0.2 Wt% is recommended.)

(3) Soldering by Soldering Iron

Peak Temperature (lead part temperature)
 Time (each pins)
 350°C or below
 3 seconds or less

• Flux Rosin flux containing small amount of chlorine

(The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

- (a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead
- (b) Please be sure that the temperature of the package would not be heated over 100°C
- (4) Cautions
  - Fluxes

Avoid removing the residual flux with freon-based and halogens-based (chlorine-based) cleaning solvent .

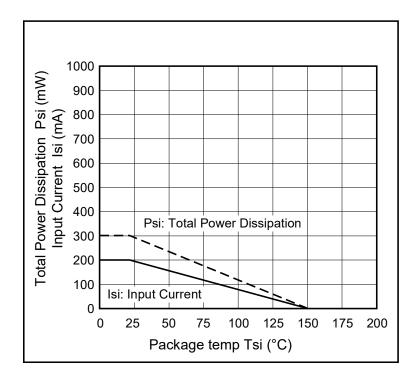
2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between Vcc-GND at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

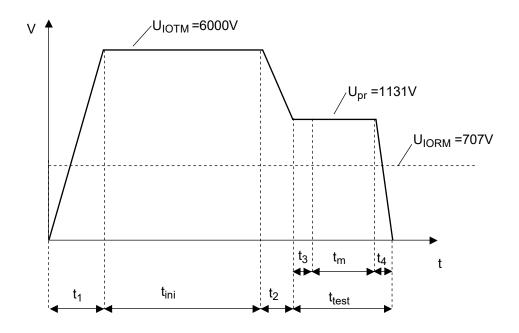
### SPECIFICATION OF VDE MARKS LICENSE DOCUMENT

Parameter	Symbol	Rating	Unit
Climatic test class (IEC 60068-1/DIN EN 60068-1)		55/100/21	
Dielectric strength maximum operating isolation voltage			
Test voltage (partial discharge test, procedure a for type test and random test)	UIORM	707	$V_{peak}$
$U_{pr} = 1.6 \times U_{IORM}$ , $P_d < 5 pC$	Upr	1 131	$V_{peak}$
Test voltage (partial discharge test, procedure b for all devices) $U_{pr} = 1.875 \times U_{IORM},  P_d < 5 \; pC$	Upr	1 326	$V_peak$
Highest permissible overvoltage	Uютм	6 000	V <sub>peak</sub>
Degree of pollution (DIN EN 60664-1 VDE 0110 Part 1)		2	
Comparative tracking index (IEC 60112/DIN EN 60112 (VDE 0303 Part 11))	CTI	175	
Material group (DIN EN 60664-1 VDE 0110 Part 1)		III a	
Storage temperature range	T <sub>stg</sub>	-55 to +125	°C
Operating temperature range	TA	-55 to +100	°C
Isolation resistance, minimum value			
V <sub>IO</sub> = 500 V dc at T <sub>A</sub> = 25°C	Ris MIN.	10 <sup>12</sup>	Ω
V <sub>IO</sub> = 500 V dc at T <sub>A</sub> MAX. at least 100°C	Ris MIN.	10 <sup>11</sup>	Ω
Safety maximum ratings (maximum permissible in case of fault, see thermal			
derating curve)		4=0	20
Package temperature	Tsi	150	°C
Current (input current I₅, Psi = 0)	lsi	200	mA
Power (output or total power dissipation)	Psi	300	mW
Isolation resistance			
V <sub>IO</sub> = 500 V dc at T <sub>A</sub> = Tsi	Ris MIN.	10 <sup>9</sup>	Ω

## Dependence of maximum safety ratings with package temperature



#### **Destructive Test, Type and Sample Test** Method a)

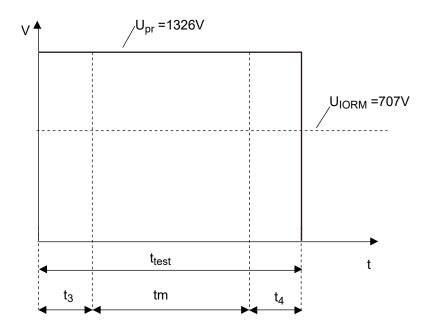


 $t_1, t_2 = 1 \text{ to } 10 \text{ sec}$  $t_3, t_4 = 1 \text{ sec}$ 

 $t_{m(PARTIAL\ DISCHARGE)}$ = 10 sec  $t_{test}$  = 12 sec

 $t_{ini}$  = 60 sec

#### Method b) Non-destructive Test, 100% Production Test



 $t_3, t_4 = 0.1 \text{ sec}$  $t_{m(PARTIAL\ DISCHARGE)}$ = 1.0 sec  $t_{test}$  = 1.2 sec

Caution

GaAs Products

This product uses gallium arsenide (GaAs).

GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.

- Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
- Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
- 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
- Do not burn, destroy, cut, crush, or chemically dissolve the product.
- Do not lick the product or i any way allow it to enter the mouth.

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